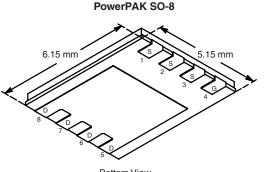


Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)	
30	0.0040 at V _{GS} = 10 V	25	47	
	0.0048 at V_{GS} = 4.5 V	23	47	



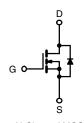
Bottom View Ordering Information: Si7886ADP-T1-E3 (Lead (Pb)-free) Si7886ADP-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free available
- TrenchFET[®] Power MOSFET
- Optimized for "Low Side" Synchronous Rectifier Operation
- New Low Thermal Resistance PowerPAK $^{\textcircled{R}}$ Package with Low 1.07 mm Profile
- 100 % R_g Tested

FEATURES

- DC/DC Converters
- Synchronous Rectifiers



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unles	ss otherwise n	oted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	30		V
Gate-Source Voltage		V _{GS}	± 12		
Continuous Drain Current (T ₁ = 150 °C) ^a	T _A = 25 °C	I _D	25	15	
Continuous Drain Current $(T_j = 150^{\circ} \text{ C})^{\circ}$	T _A = 70 °C		20	12	
Pulsed Drain Current (10 µs Pulse Width)		I _{DM}	60		А
Continuous Source Current (Diode Conduction) ^a		۱ _S	4.5	1.6	
Avalanche Current	L = 0.1 mH	I _{AS}	50 125		
Single Pulse Avalanche Energy	L = 0.11111	E _{AS}			mJ
	T _A = 25 °C	P _D	5.4	1.9	W
Maximum Power Dissipation ^a	T _A = 70 °C		3.4	1.2	vv
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		0°
Soldering Recommendations (Peak Temperature) ^{b, c}			260		C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	18	23	°C/W
Maximum Junction-to-Ambient*	Steady State		50	65	
Maximum Junction-to-Case (Drain)	Steady State		1.0	1.5	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.



Vishay Siliconix



Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static			•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.6	1	1.5	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 12 V$	$V_{DS} = 0 V, V_{GS} = \pm 12 V$		± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	= 30 V, V _{GS} = 0 V		1	
		V_{DS} = 30 V, V_{GS} = 0 V, T_{J} = 55 °C			5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, $V_{GS} = 10$ V	30			А
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 25 A	0.0032 0.00		0.0040	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 23 \text{ A}$		0.0037	0.0048	Ω
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 25 \text{ A}$		90		S
Diode Forward Voltage ^a	V _{SD}	$I_{S} = 2.9 \text{ A}, V_{GS} = 0 \text{ V}$		0.7	1.1	V
Dynamic ^b	<u> </u>		<u> </u>	•	<u> </u>	
Input Capacitance	C _{iss}			6450		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{SS} = 0 \text{ V}, f = 1 \text{ kHz}$		873		
Reverse Transfer Capacitance	C _{rss}			402		
Total Gate Charge	Qg			47	60	
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 25 A		12.5		nC
Gate-Drain Charge	Q _{gd}			9.0		
Gate Resistance	Rg		0.5	1.0	1.5	Ω
Turn-On Delay Time	t _{d(on)}			17	30	
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		14	25	ns
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 1.0 A, V_{GEN} = 10 V, R_G = 6 Ω		158	230	
Fall Time	t _f			43	65	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.9 A, di/dt = 100 A/μs		50	80	

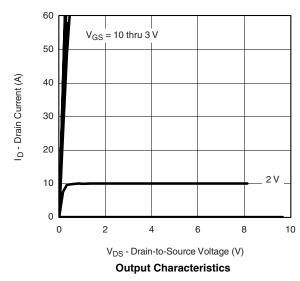
Notes:

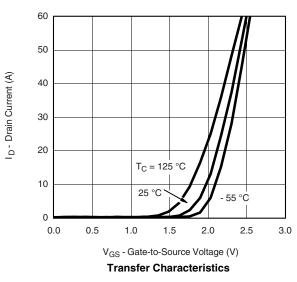
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

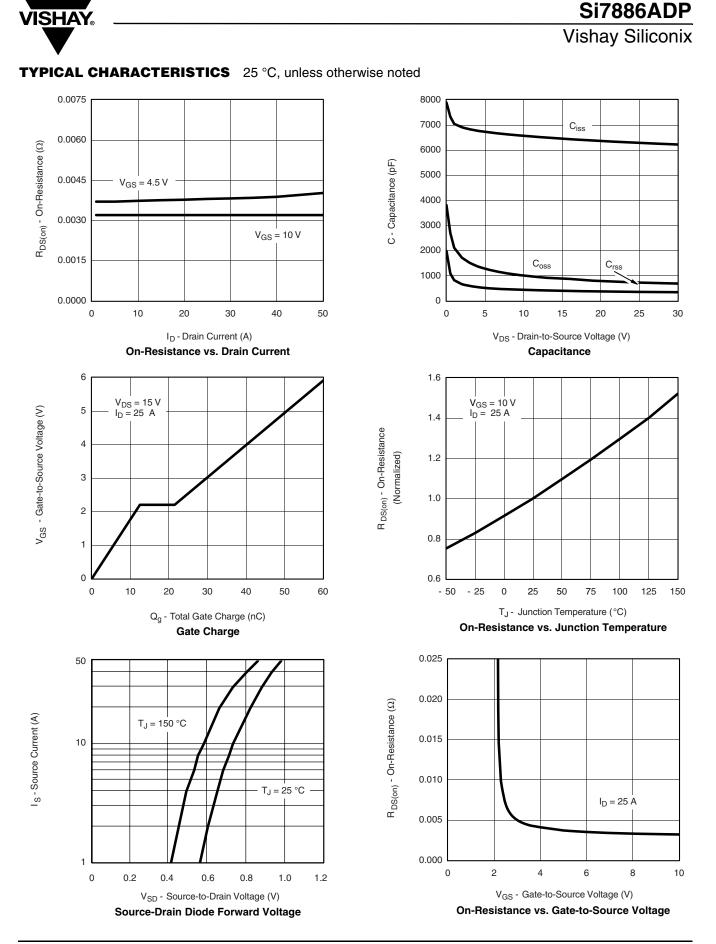
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







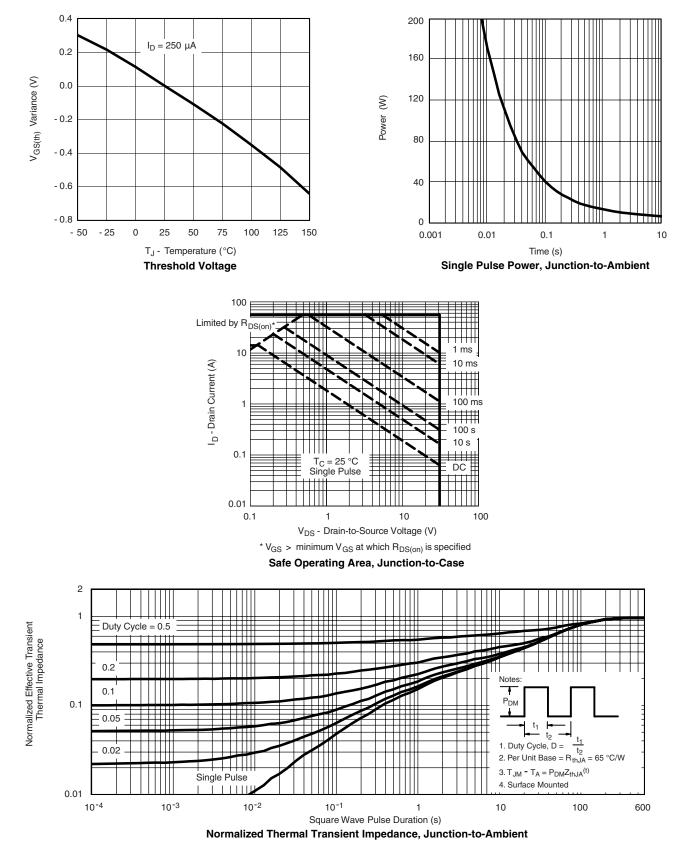
Document Number: 73156 S-80440-Rev. D, 03-Mar-08

Si7886ADP

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

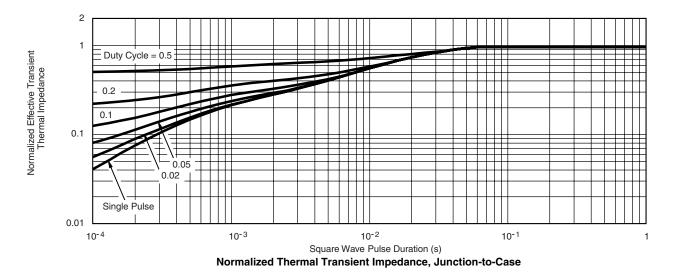




Si7886ADP

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?73156.



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